



Material Content Data Sheet



Sales Product Name	TLE9869QXA20			Issued	27. September 2017			
MA#	MA001336810							
Package	PG-VQFN-48-31			Weight*	129.94 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.821	3.71	3.71	37099	37099
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		551	
	non noble metal	iron	7439-89-6	1.433	1.10		11029	
wire	non noble metal	copper	7440-50-8	58.193	44.78	45.95	447834	459552
	non noble metal	copper	7440-50-8	0.594	0.46	0.46	4572	4572
	encapsulation	organic material	carbon black	1333-86-4	0.181	0.14		1394
encapsulation	plastics	epoxy resin	-	7.669	5.90		59018	
	inorganic material	silicondioxide	60676-86-0	52.536	40.43	46.47	404296	464708
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19981	19981
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4724	4724
glue	plastics	epoxy resin	-	0.280	0.22		2154	
	noble metal	silver	7440-22-4	0.937	0.72	0.94	7210	9364
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com